

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5637497

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SMARTER MICROELECTRONICS	07/24/2019
RECEIVING PARTY DATA	
Name:	SMARTER MICROELECTRONICS (SHANGHAI) CO., LTD.
Street Address:	RM203, 500 BIBO ROAD, PUDONG DISTRICT
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203
PROPERTY NUMBERS Total: 2	
Property Type	Number
Patent Number:	8466745
Patent Number:	8497738
CORRESPONDENCE DATA	
Fax Number:	(608)334-4315
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	6083344315
Email:	fmmfinnmar@gmail.com
Correspondent Name:	SYNCODA LLC
Address Line 1:	208 EUPHORIA CIR
Address Line 4:	CARY, NORTH CAROLINA 27519
ATTORNEY DOCKET NUMBER:	13205727-13214229
NAME OF SUBMITTER:	FENG MA
SIGNATURE:	/Feng Ma/
DATE SIGNED:	07/26/2019
Total Attachments: 2	
source=13205727-13214229-Assign-P#page1.tif	
source=13205727-13214229-Assign-P#page2.tif	

ASSIGNMENT

SMARTER MICROELECTRONICS (the "ASSIGNOR") is owner of:

U.S. Patent Number: 8466745, issued on June 18, 2013, filed as Application Serial Number 13214229 on August 21, 2011, titled HYBRID RECONFIGURABLE MULTI-BANDS MULTI-MODES POWER AMPLIFIER MODULE, which claims priority to U.S. Provisional Patent Application No. 61/376,753, filed Aug. 25, 2010;

U.S. Patent Number: 8497738, issued on July 30, 2013, filed as Application Serial Number 13205727 on August 9, 2011, titled BROADBAND POWER COMBINING METHOD AND HIGH POWER AMPLIFIER USING SAME, which claims priority to U.S. Provisional Patent Application No. 61/372,551, filed Aug. 11, 2010;

(the "PATENTS").

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned (hereinafter referred to as "ASSIGNOR"), do hereby:

SELL, ASSIGN AND TRANSFER to SMARTER MICROELECTRONICS (SHANGHAI) CO., LTD. (the "Assignee"), having a place of business at RM203, 500 Bibo Road, Pudong District, Shanghai 201203, China, the entire (100%) right, title and interest for the United States and all foreign countries in the PATENTS and to any and all improvements which are disclosed in the above-identified PATENTS; such applications, patents, and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements for the entire terms of any patents, reissues or extensions that may issue from foreign applications, divisions, continuations in whole or part or substitute applications filed claiming the benefit of the PATENTS; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such PATENTS in the United States;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for vesting title to such improvements in the Assignee, and for securing, maintaining and enforcing proper patent protection for such improvements;

TO BE BINDING on the heirs; assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

ASSIGNOR HEREBY REPRESENTS AND WARRANTS that ASSIGNOR has the full and unencumbered right to sell, assign, and transfer the interests sold, assigned, and transferred herein, and that ASSIGNOR has not executed and will not execute any document or instrument in conflict herewith. The right, title and interest conveyed in this Assignment is to be held and enjoyed by Assignee and Assignee's successors as fully and exclusively as it would have been held and enjoyed by ASSIGNOR had this Assignment not been made.

ASSIGNOR HEREBY GRANTS to the agents and attorneys of Syncoda LLC the power and authority to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

The assignment of said invention is effective as of the earlier of (1) the date of execution shown below or (2) the filing date of the first filed of said PATENTS.

The undersigned (whose title is supplied below) is authorized to act on behalf of the ASSIGNOR.	
Signature: <u>Yachui Guo</u>	Date: <u>01/26/2019</u>
Name: <u>GUO, Yachui</u>	
Title: <u>COO</u> <u>SMARTER MICROELECTRONICS</u>	